

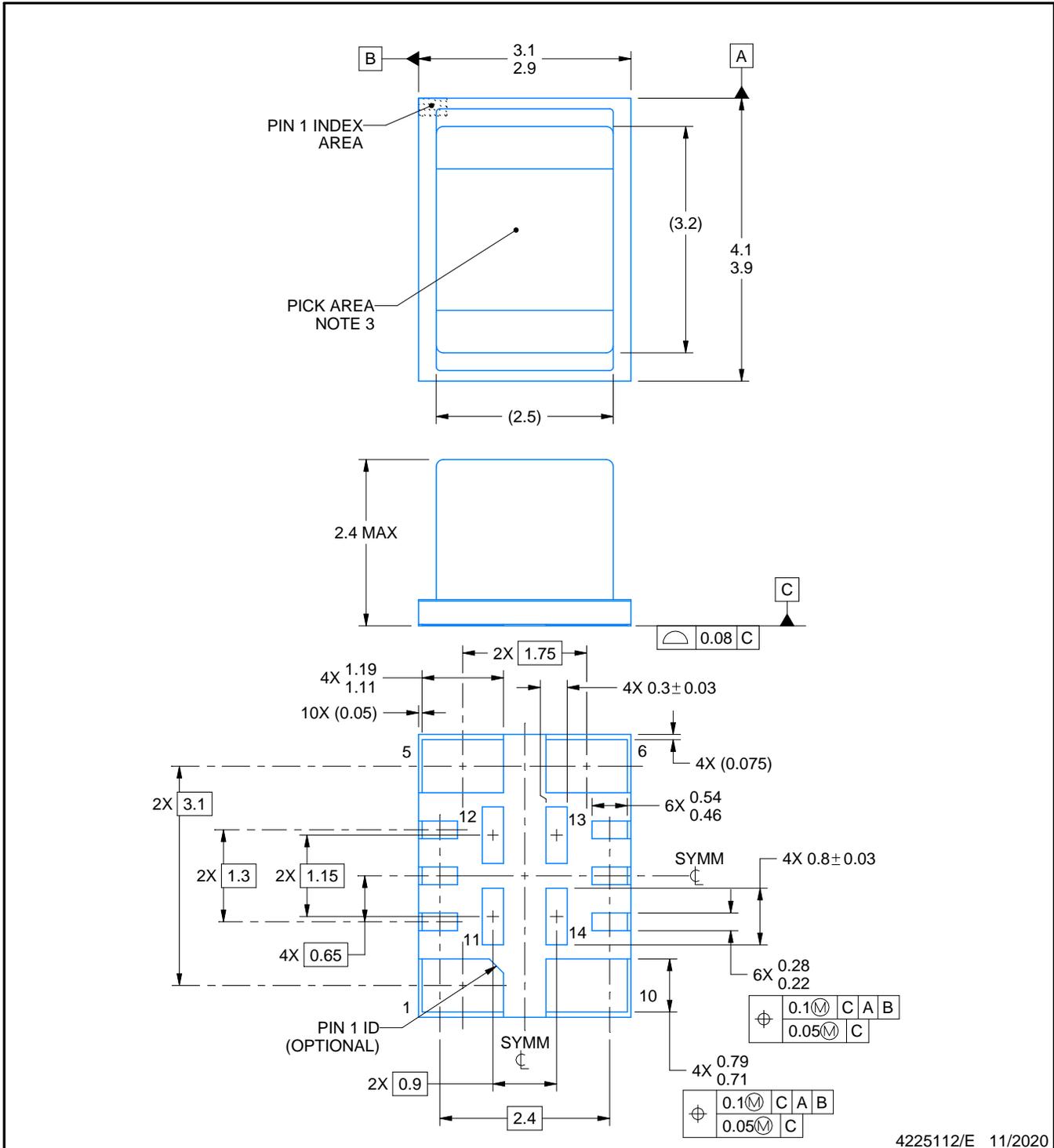


PACKAGE OUTLINE

SIL0014B

uSIP™ - 2.4 mm max height

MICRO SYSTEM IN PACKAGE



4225112/E 11/2020

MicroSiP is a trademark of Texas Instruments

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Pick and place nozzle \varnothing 1.3 mm or smaller recommended.
4. The package thermal pads must be soldered to the printed circuit board for thermal and mechanical performance.

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